

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

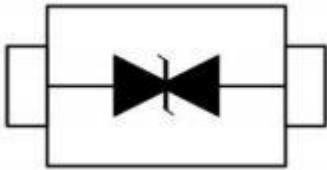


PLED

Product data sheet

www.msksemi.com

PIN CONFIGURATION



SOD-323

FEATURES

- IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- 350 Watts Peak Pulse Power per (tp=8/20 μs)
- Protects one I/O line (bidirectional)
- Low clamping voltage
- Working voltages:
3.3V, 5V, 8V, 12V, 15V, 18V, 20V, 24V, 36V
- Low leakage current

MACHANICAL DATA

- SOD-323 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- High temperature soldering guaranteed:
260C/10s
- Reel size: 7 inch
- MSL 1

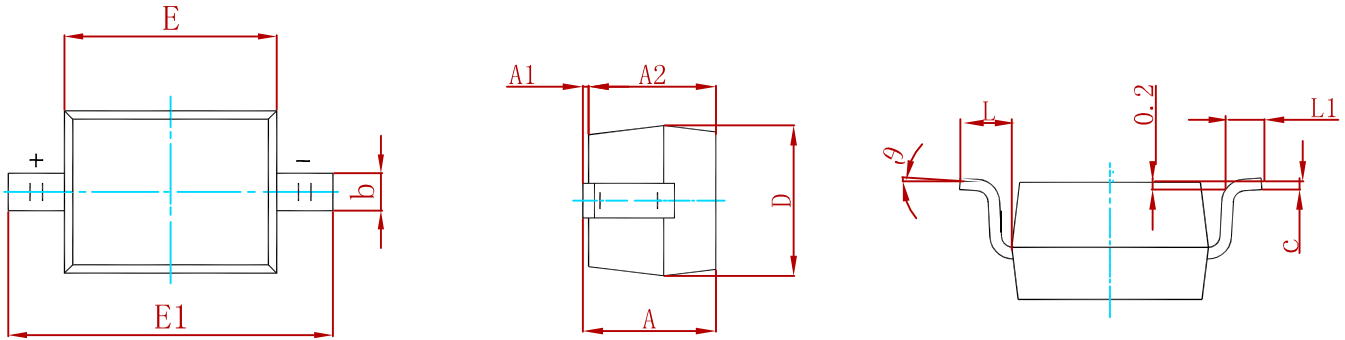
APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports.
- Peripherals

ABSOLUTE MAXIMUM RATING			
Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
P _{PP}	Peak Pulse Power (8/20μs)	350	W
T _{OPT}	Operating Temperature	-55/+150	°C
T _{STG}	Storage Temperature	-55/+150	°C
T _L	Lead Soldering Temperature	260 (10 sec.)	°C

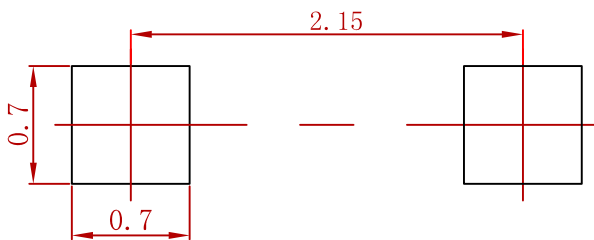
ELECTRICAL CHARACTERISTICS (T _{amb} =25°C)									
P/N	MARK	V _{RWM}	V _B	I _r	V _{c@1A}	V _c		I _R	C _T
		(V) max	(V) min	(mA)	(V) (max.)	(max.)	(@A)	(μA) (max.)	(pF) (max.)
PSD03C	2A	3.3	4.0	1	7.5	16.0	20	40	450
PSD05C	2B	5.0	6.0	1	9.8	18.0	17	10	200
PSD08C	2C	8.0	8.5	1	13.4	24.0	15	2	120
PSD12C	2D	12.0	13.3	1	19.0	32.0	11	1	75
PSD15C	2J	15.0	16.7	1	24.0	38.0	10	1	68
PSD18C	2K	18.0	20.0	1	29.0	45.0	9	1	57
PSD20C	2L	20.0	22.3	1	35.0	50.0	8	1	52
PSD24C	2H	24.0	26.7	1	43.0	52.0	7	1	50
PSD36C	2N	36.0	40.0	1	60.0	75.0	4.5	1	35

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:**
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PSDXXC	SOD-323	3000

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